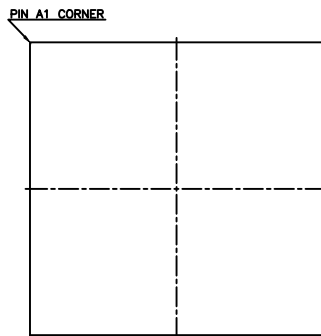
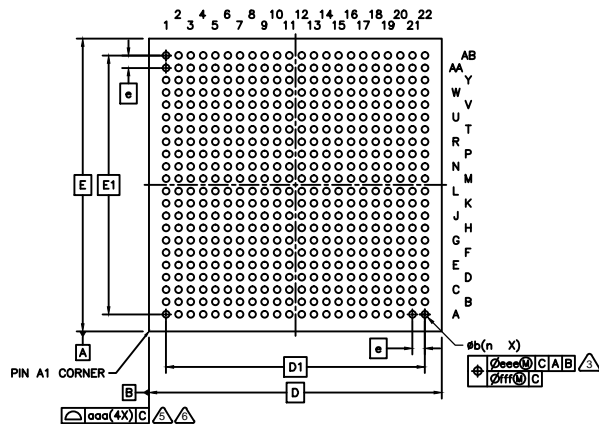
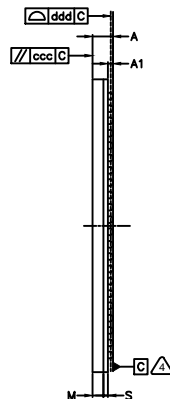




TOP VIEW



SIDE VIEW



BOTTOM VIEW

	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Body Size:	X Y	E D	19.000 19.000	
Ball Pitch:	e		0.800	
Total Thickness:	A	—	—	1.700
Mold Cap Thickness:	M		0.700	Ref.
Substrate Thickness:	S		0.300	Ref.
Ball Diameter:			0.450	
Stand Off:	A1	0.250	—	0.400
Ball Width:	b	0.400	0.450	0.500
Package Edge Tolerance:	aaa		0.150	
Mold Parallelism:	ccc		0.200	
Coplanarity:	ddd		0.200	
Ball Offset (Package):	eee		0.150	
Ball Offset (Ball):	fff		0.080	
Ball Count:	n		484	
Edge Ball Center to Center:	X Y	E1 D1	16.800 16.800	

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square .
- PRIMARY DATUM \square AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- JEDEC REFERENCE: MO-275

Title: Package Outline Drawing	Pkg Type: CABGA	Document No: POD-250081	
Product Family: LFMXO4	Pin Count: 484		
Product Name: LFMXO4-110-BBG484	Pkg Size: 19x19 mm	Rev: A	

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